



SPECIFICATION FOR APPROVAL

Customer: ACUWA

Customer's P/N:

LianZhen P/N: SCDS104R-101M-AC1W

Drew Date: 2021.04.14

APPROVAL STAMP

Please sign back within one week

 聯 振 電 子 (深 圳) 有 限 公 司

LIANZHEN ELECTRONICS (SHEN ZHEN) CO.,LTD.

8th Building, Yangbei Industrial Park, Huangtian Community, Hangcheng

Street, Baoan District, Shenzhen City, Guangdong Province, PRC

深圳市寶安區航城街道黃田社區楊貝工業區第八棟

TEL:0755-27911508 27798793 FAX:0755-27918330

<http://www.lianzhen.cn>

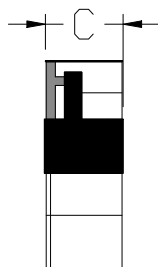
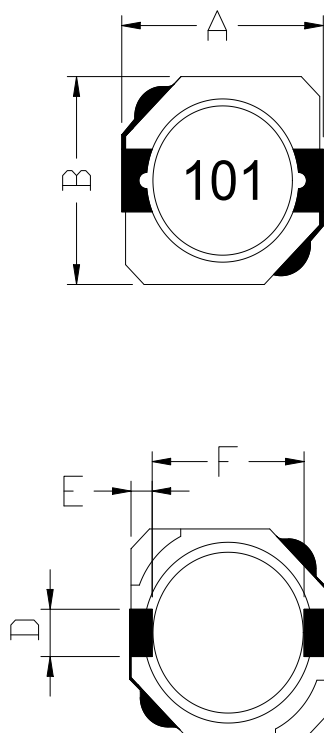
ECN History List

[illegible]

PART NUMBER	Inductance L0 (uH) ±20%	I_{RMS} (Amp) Typ	I_{SAT} (Amp) Typ	R_{DC} (mΩ) Max
SCDS104R-101M-AC1W	100	1.2	1.2	300

Note:

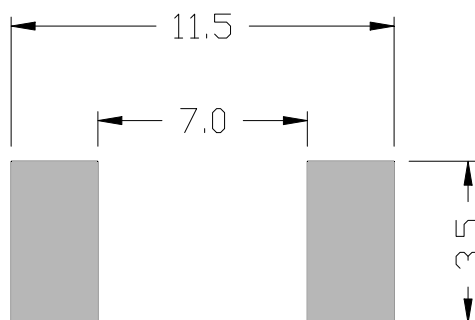
- *. Operating temperature -40°C ~ +125°C.
- *. Storage temperature -40°C ~ +125°C.
- *. All test data is referenced to 25°C ambient, Inductance value test Equipments:
CH3302 or WK3255B or HP4284, R_{DC} test equipments CH16502.....
- *. Inductance value test condition Frequency 100KHz and 1.0Vrms at 25°C
- *. I_{RMS}: The current will cause the coil temperature rise approximately 40°C
- *. I_{SAT}: The current will cause L0 to drop approximately 30% typical



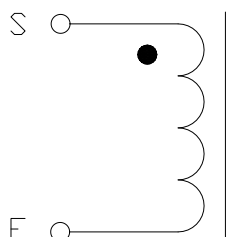
Item	mm
A	10.2±0.3
B	10.0±0.3
C	3.8±0.2
D	3.0±0.5
E	1.2±0.5
F	7.7±0.5

*.Marking: 101

LAND PATTERN DIMENSIONS

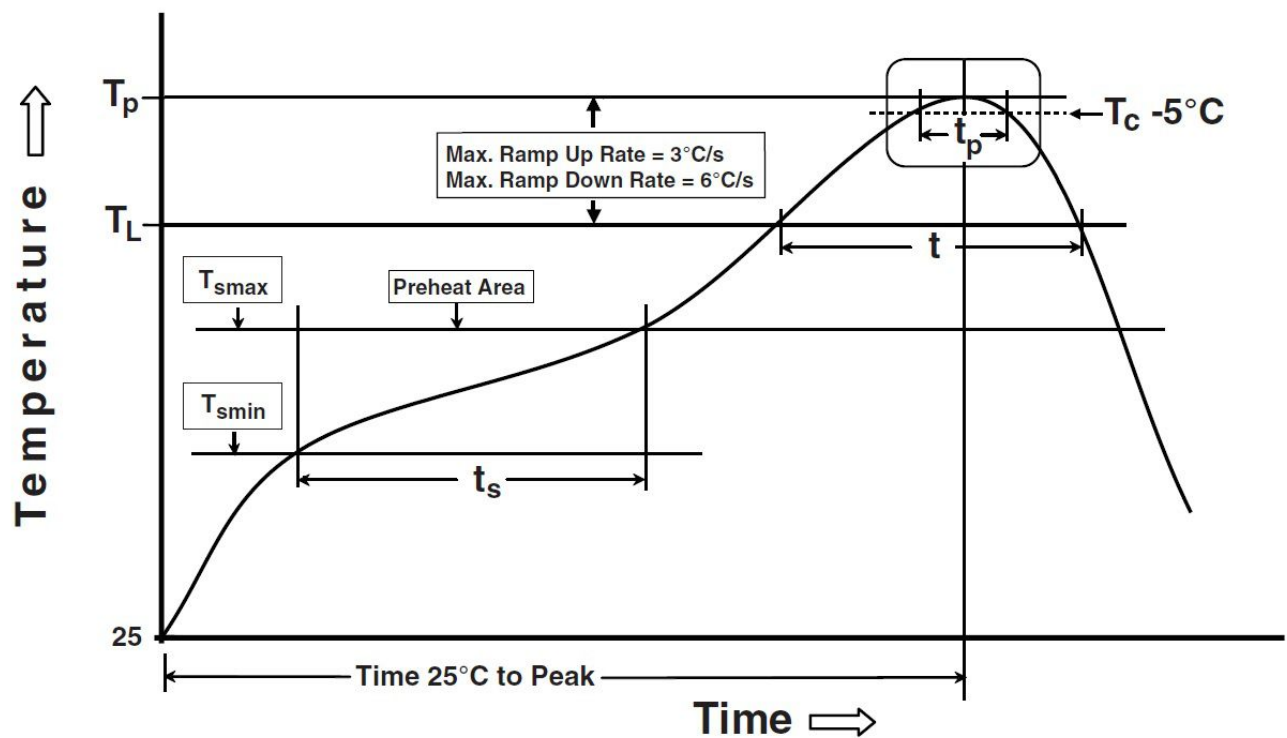


SCHEMATIC



NO.	Item	Specification and Description
1	Core	Ferrite Core
2	Wire	2UEWH
3	Solder	Sn99.3 Cu0.7(9930)
4	Base	C104R-2 P1
5	Ink	Black Ink(Resin)
6	Adhesive	Epoxy

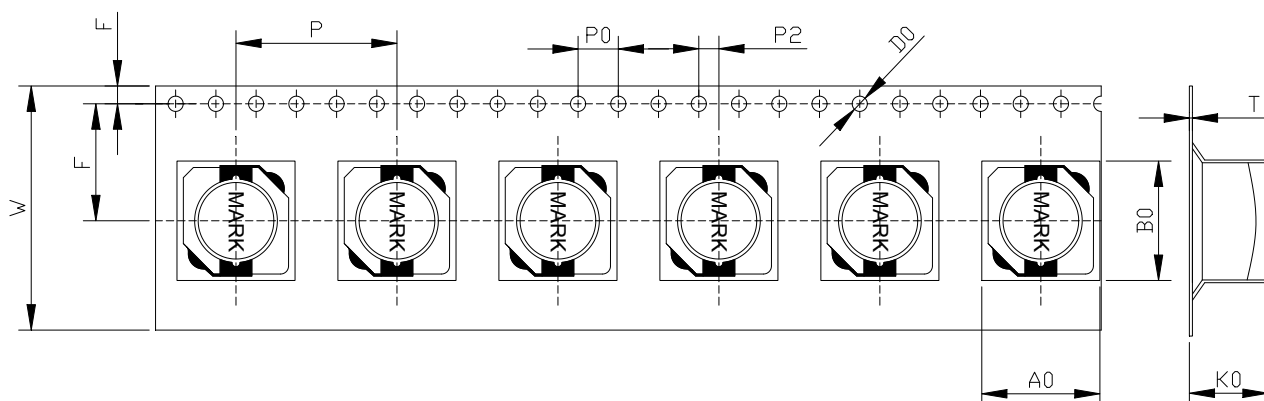
ITEMS	TEST CONDITION	SPECIFICATIONS	REFERENCES
High temperature Storage	1. Precondition is requirement 2. +125 °C, 1000hrs 3. Measurements shall be taken at 0 (post preconditioning), 168hrs, 500hrs, 1000hrs.	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all	JESD22-A103 or MIL-STD-202 Method 108
Low Temperature Storage	1. Preconditioning is required. 2. -55 °C, 1000hrs 3. Measurements shall be taken at 0 (post preconditioning), 168hrs, 500hrs, 1000hrs.	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all	JESD22-A119
Temperature Cycling	1. Precondition is requirement 2. -40°C/ +125 °C, 1000 Cycles, 30 Minutes each extreme; 3. Measurements shall be taken at 0 (post preconditioning), 250 cycles, 500 cycles, 1000 cycles.	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all	JESD22-A104 or MIL-STD-202 Method 107
High Temperature Humidity (DampHeat-Steady State)	1. Preconditioning is required. 2. 85° C, 85%RH, 1000hrs. 3. Measurements shall be taken at 0 (post preconditioning), 168hrs, 500hrs, 1000hrs.	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all	JESD22-A101 or MIL-STD-202 Method 103
Vibration	1. Frequency range : 10~2000Hz. 2. Amplitude: 1.5mm or 20 G 3. Sweep time and duration: 10~2000~10Hz for 20 minutes 4. Each four hours(12 times) in X,Y,Z direction: 12 hours in total	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all	MIL-STD-202 Method 204 or JESD22B-103
Resistance to Soldering Heat	DIP: 260+/-5°C, 10+/-1sec, 1 time, or IR Reflow: 250+/-5°C (component temp), 30 sec, 3 times or Peak temp 260 °C +5°C, 10sec, 3time.	1. Inductance, RDC change rate is within +/-10%. 2. Appearance is ok for all. 3. No inner layer crack	MIL-STD-202 Method 210 or JESD22-B106 or J-STD-020
Terminal Strength for SMD	1. Preconditioning is required. 2. With the component mounted on a PCB 3. Apply 1.8kg force to the side of a device being tested. This force shall be applied for 60 +1 seconds.	Inductance, RDC change rate is within +/-10%. Appearance is ok for all. No evidence of part being sheared off from its pad.	AEC-Q200-006



Classification Profile

Profile Feature		Lead Free Soldering
Preheat and soak	Temperature Min.(T _{smin})	150°C
	Temperature Max.(T _{smax})	200°C
	Time(T _{smin} to T _{smax})(t _s)	60-120 Seconds
Ramp-up rate (T _L to T _p)		3°C/Second Max.
Liquidous temperature (T _L)		217 °C
Time (t _L) maintained above T _L		60-150 Seconds
Classification temperature (T _c)		260°C Max
Time (t _p) within 5°C of T _c		30 Seconds Max.
Ramp-down rate (T _p to T _L)		6 °C/Second Max.
Time 25 °C to peak temperature		8 Minutes Max.
Recommended reflow soldering temperature		245°C±5 °C

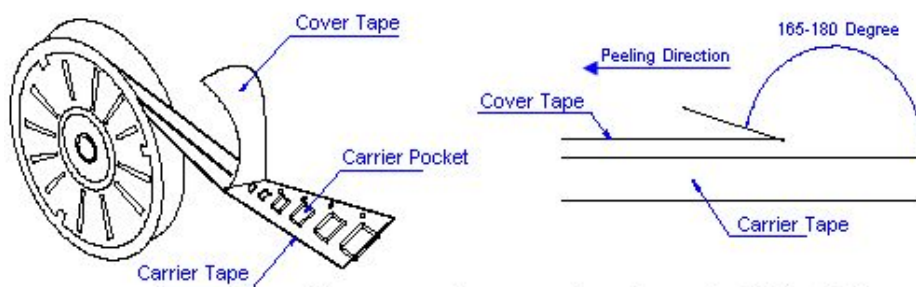
Packaging Dimension:(mm)



W	A0	B0	K0	P	F	E	P0	P2	D0	T
24.0±0.3	10.6±0.3	10.8±0.3	4.3±0.3	16.0±0.2	11.5±0.2	1.75±0.2	4.0±0.2	2.0±0.2	Ø1.5±0.1	0.35±0.1

Cover tape & peeling force

Cover tape sealing method: Manufacturing-Defined



The cover tape peeling force is 10 to 130g in arrow direction. Peeling angle between 165° and 180°.

Note:

*.1000PCS/Reel

*.Storage condition:-5℃~+40℃, 20% to 70%RH